

FIG. 1A

FIG. 1B

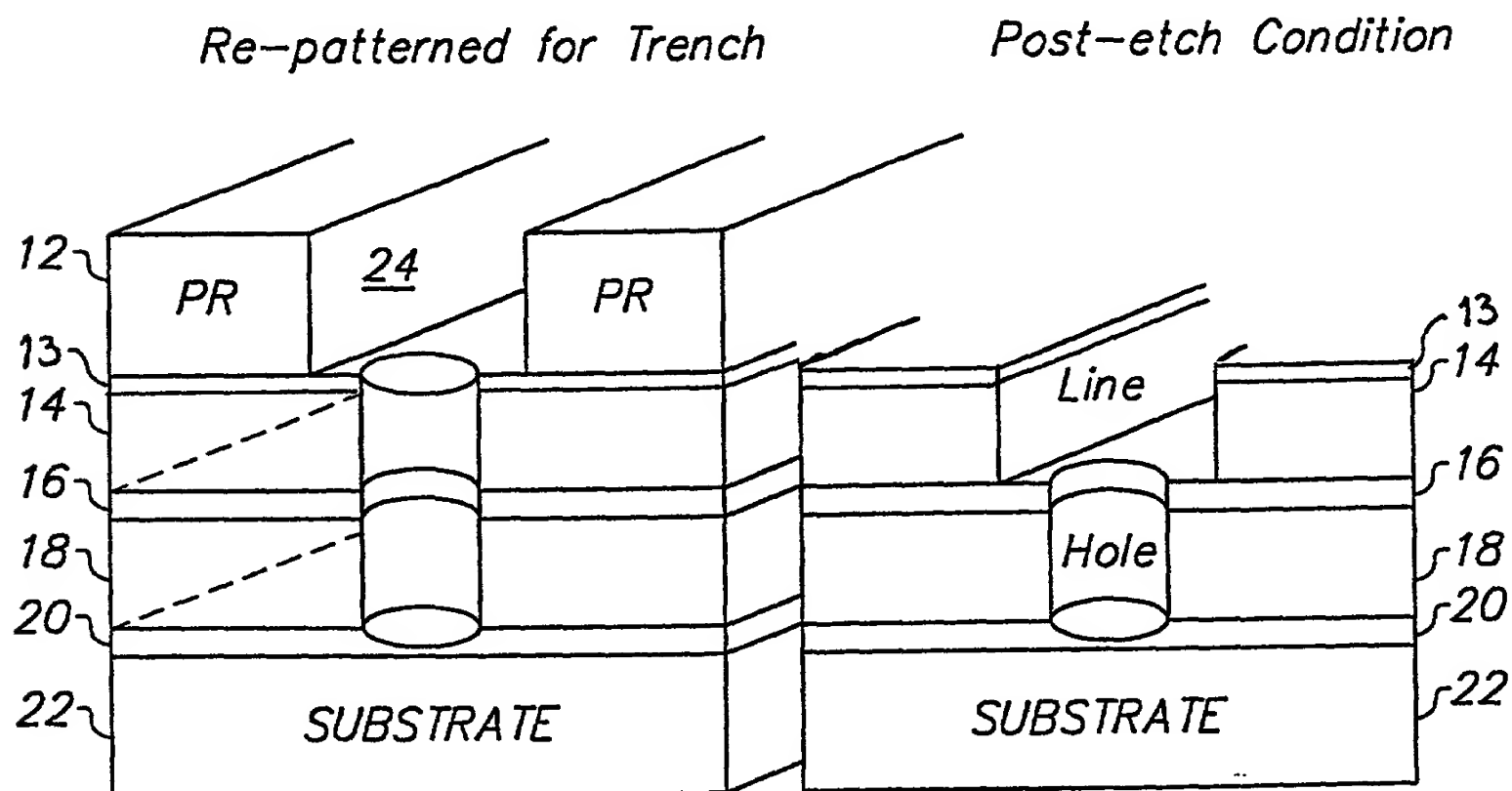


FIG. 1C

FIG. 1D

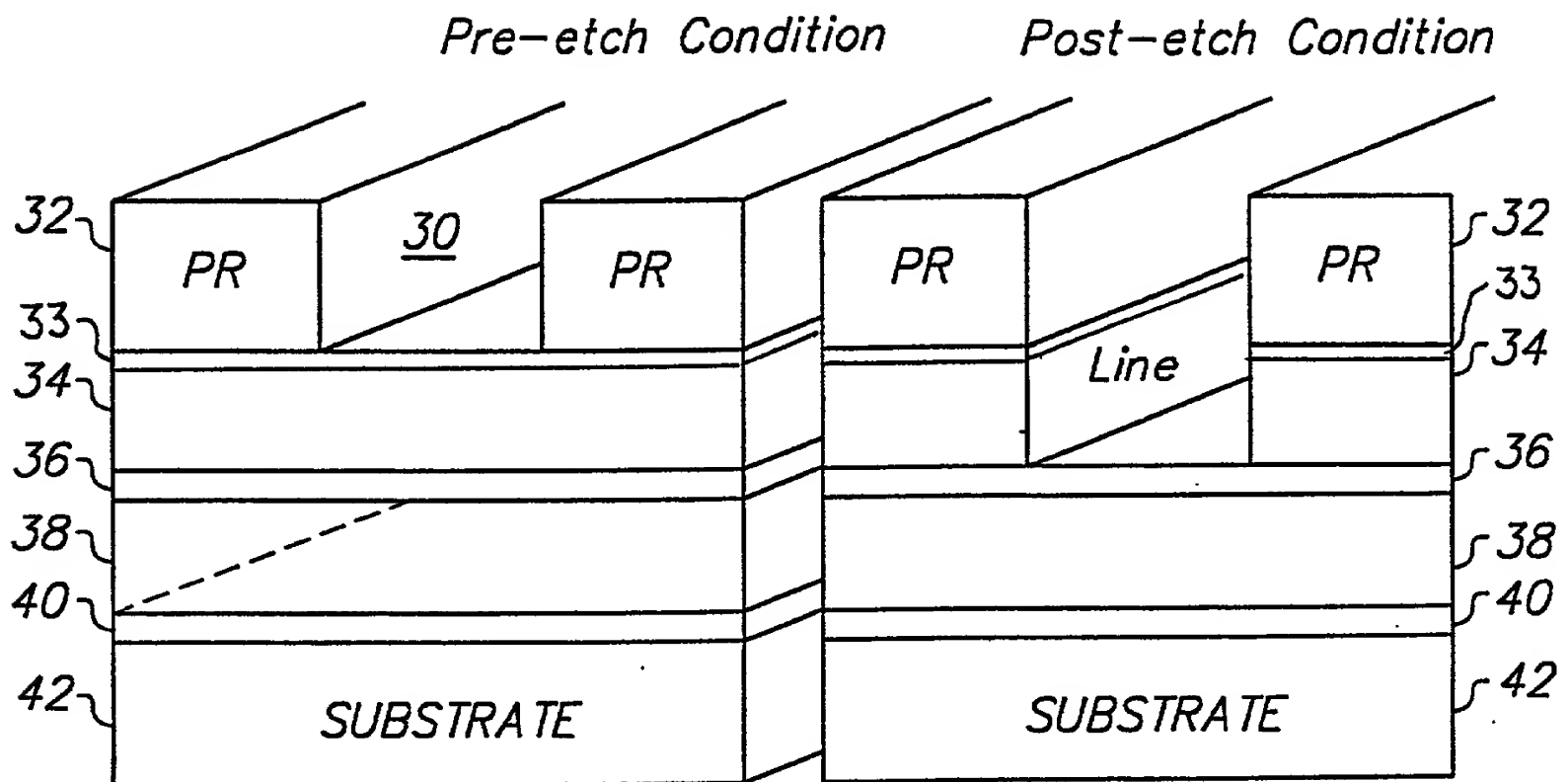


FIG. 2A

FIG. 2B

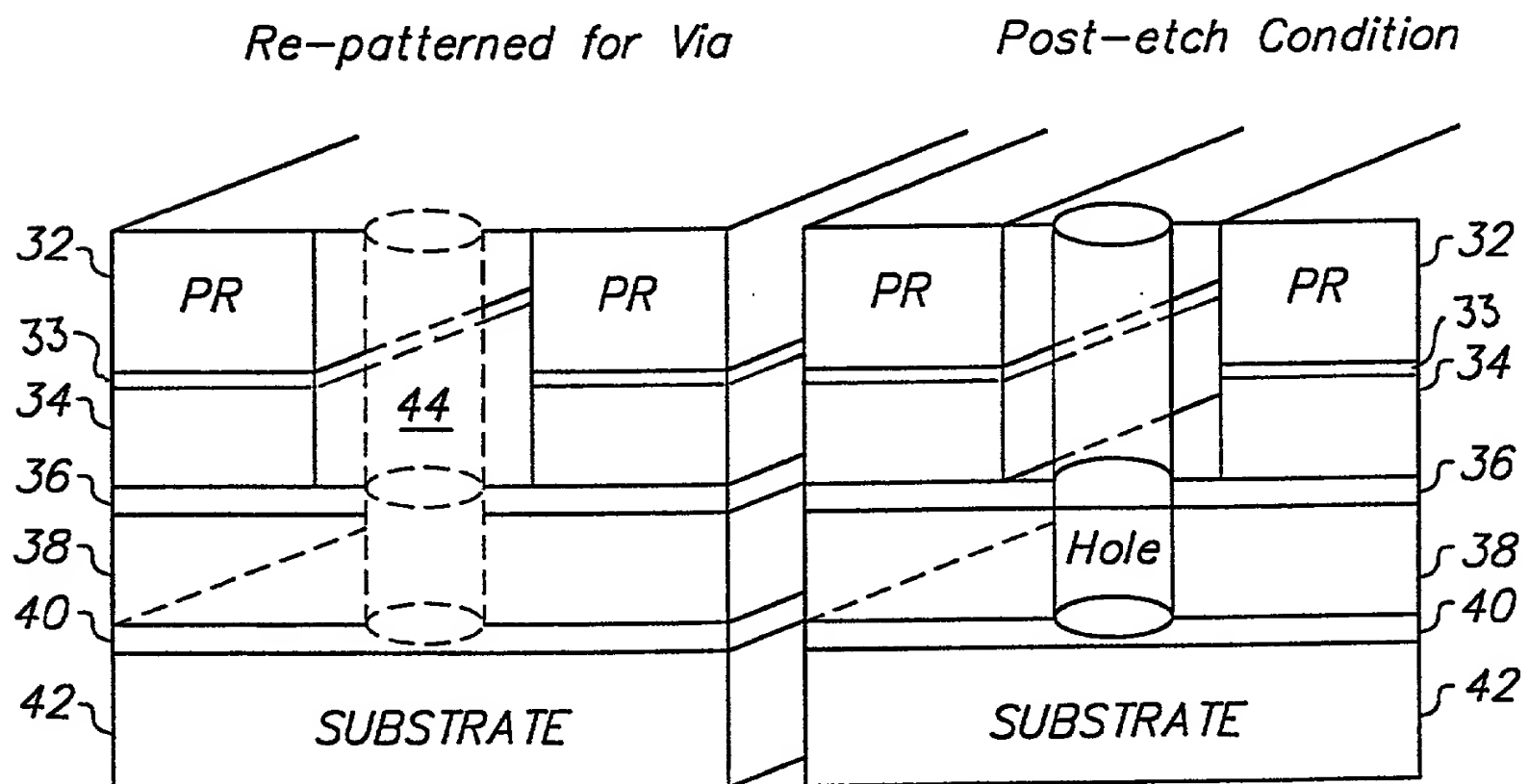


FIG. 2C

FIG. 2D

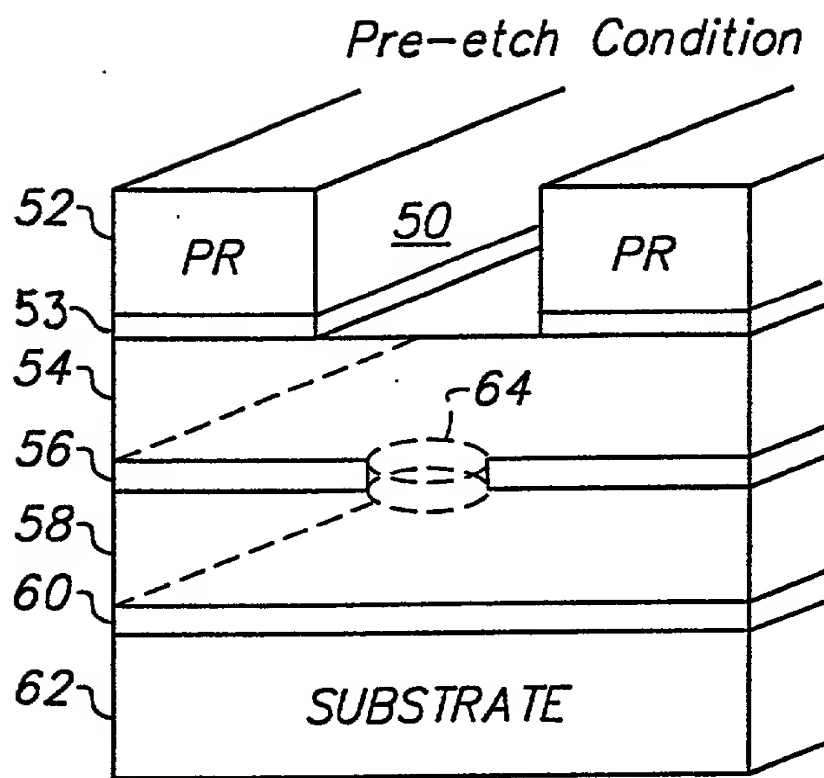


FIG. 3A

Post-etch Condition

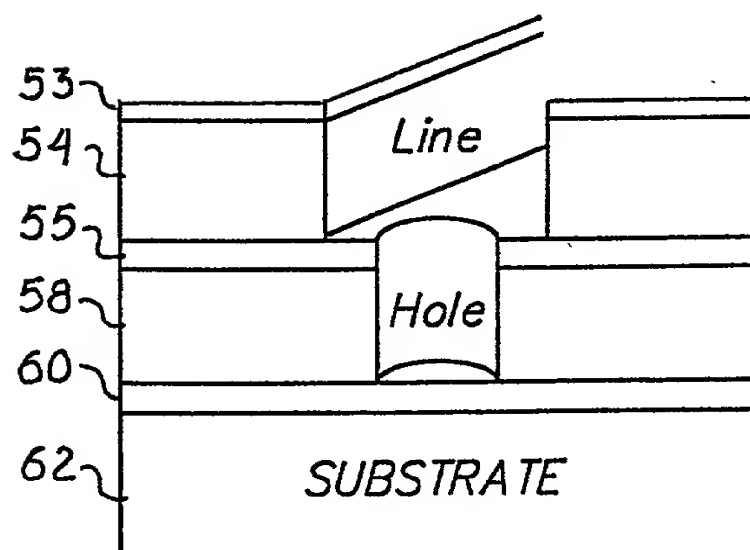


FIG. 3B

FIG. 4 is a cross-sectional view of a device 100, showing a housing 102 and a component 104. The component 104 is mounted on a base 106 and includes a series of protrusions 110. A layer 112 is disposed over the protrusions 110, and a layer 114 is disposed over the layer 112. A layer 120 is disposed over the layer 114, and a layer 122 is disposed over the layer 120. A layer 124 is disposed over the layer 122, and a layer 126 is disposed over the layer 124. A layer 118 is disposed over the layer 126. The device 100 is shown in a cross-sectional view, with the housing 102 and component 104 being the main parts of the device. The component 104 is mounted on the base 106, and the layers 110, 112, 114, 120, 122, 124, 126, and 118 are stacked on top of each other. The housing 102 is shown as a rectangular frame surrounding the component 104.

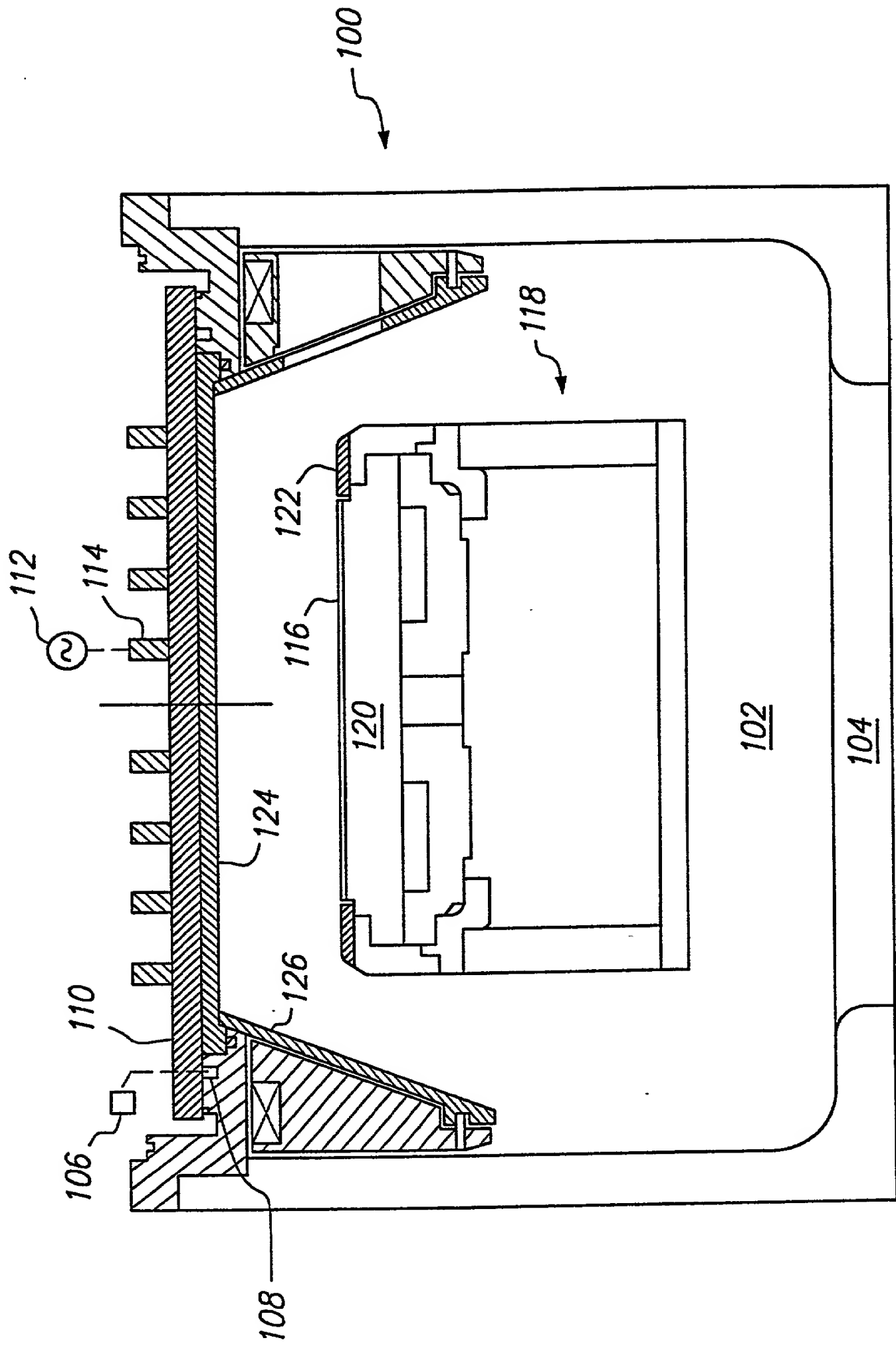


FIG. 4

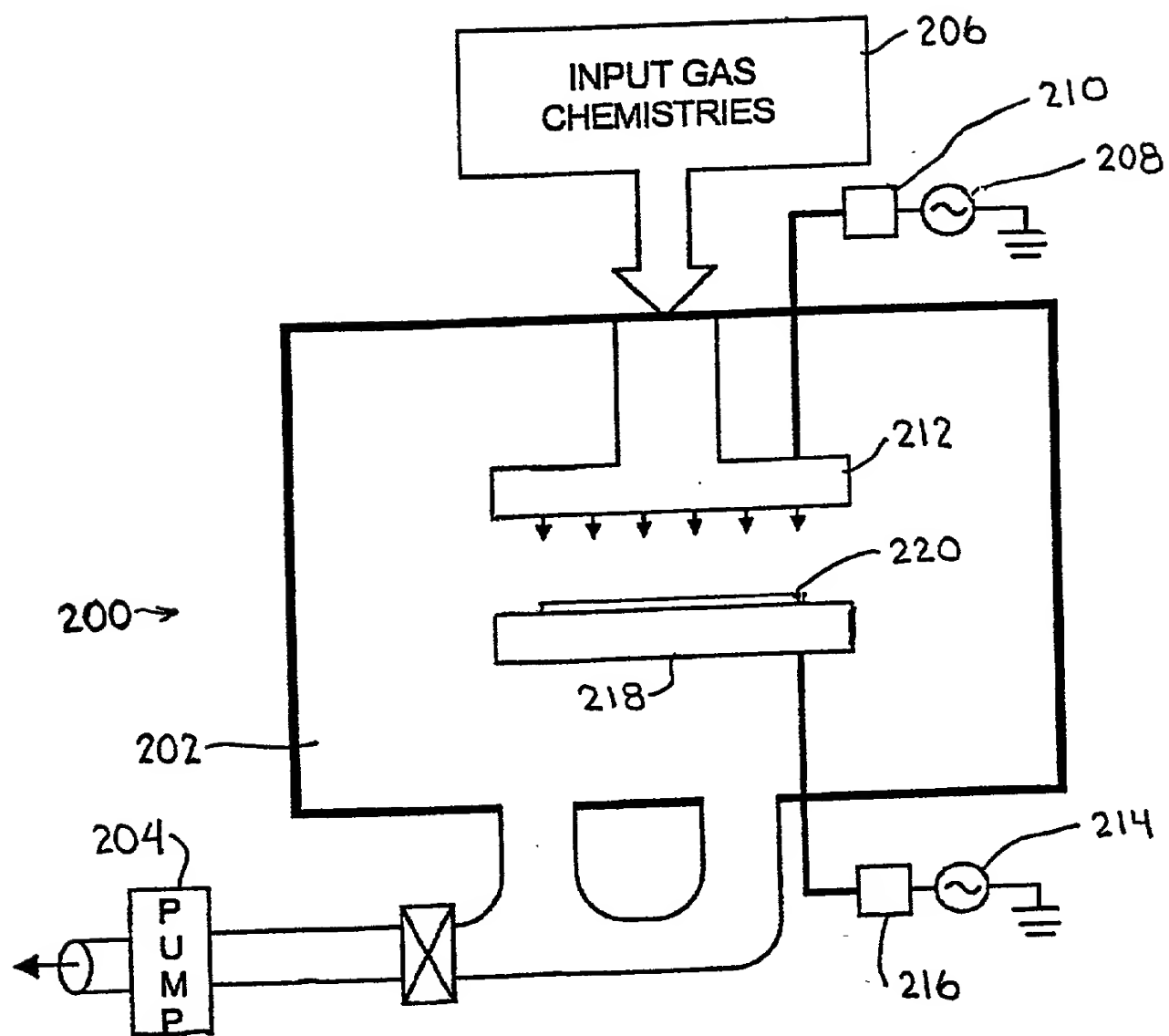


FIG. 5

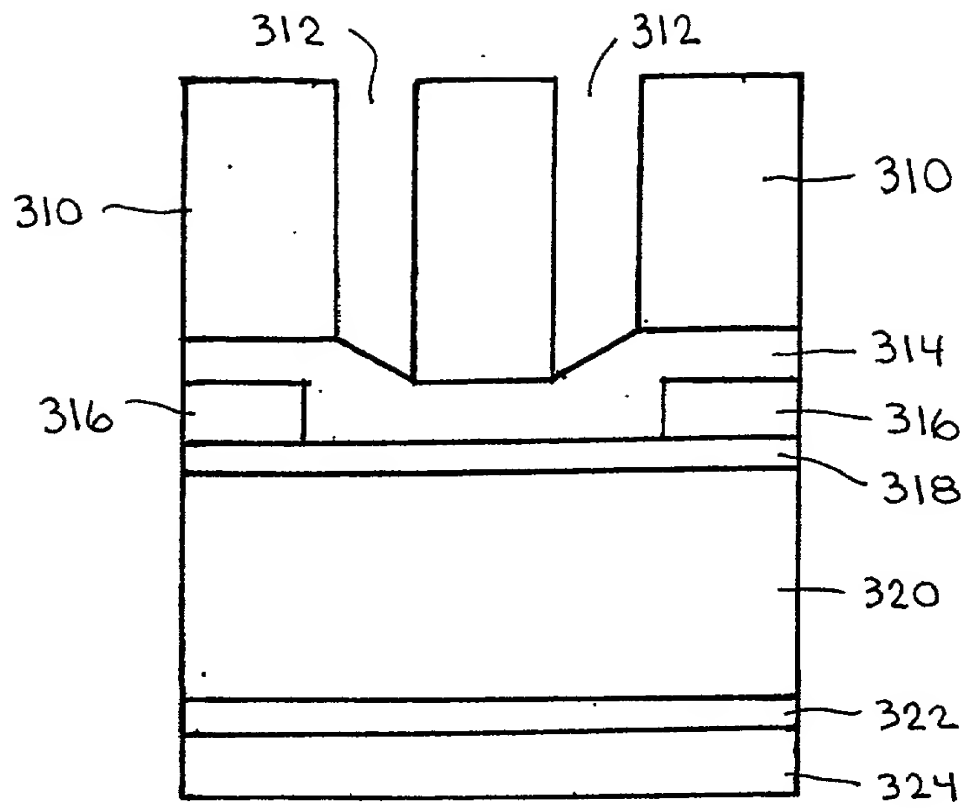


FIG. 6A

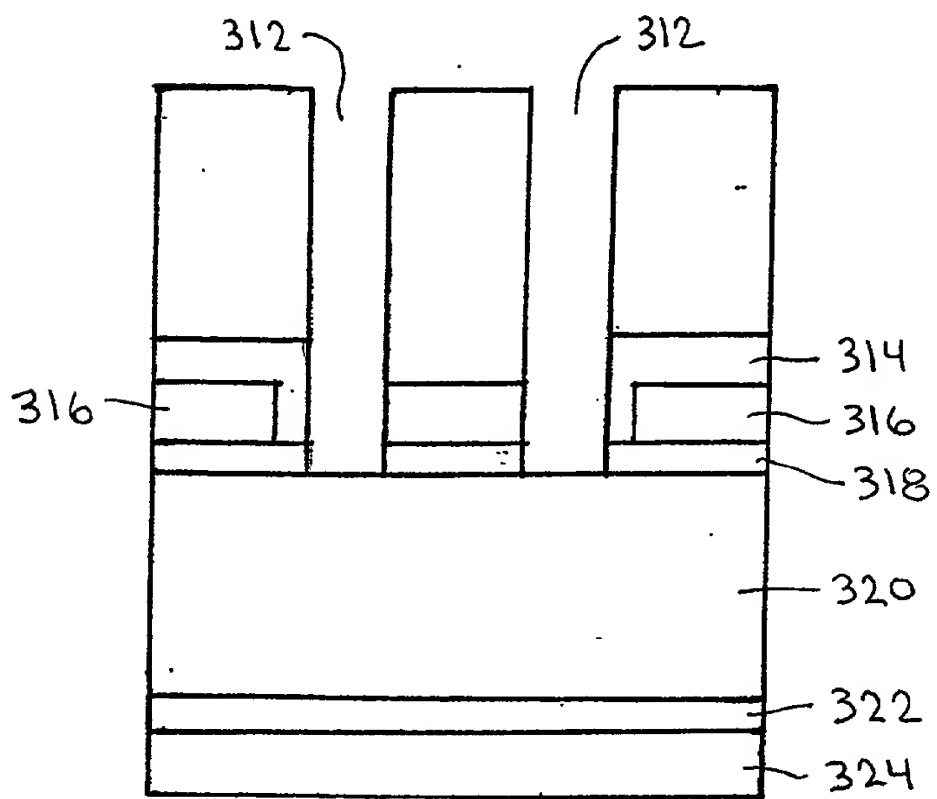


FIG. 6B

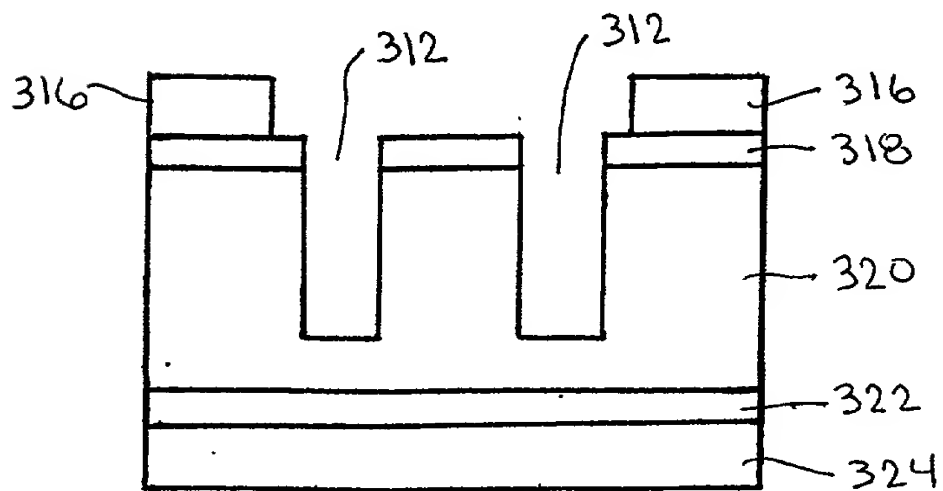


FIG. 6C

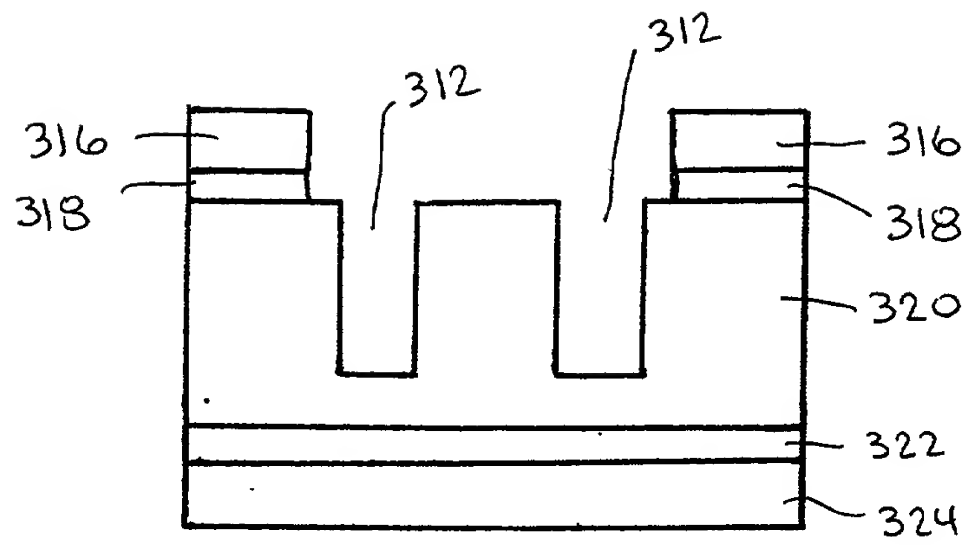


FIG. 6D

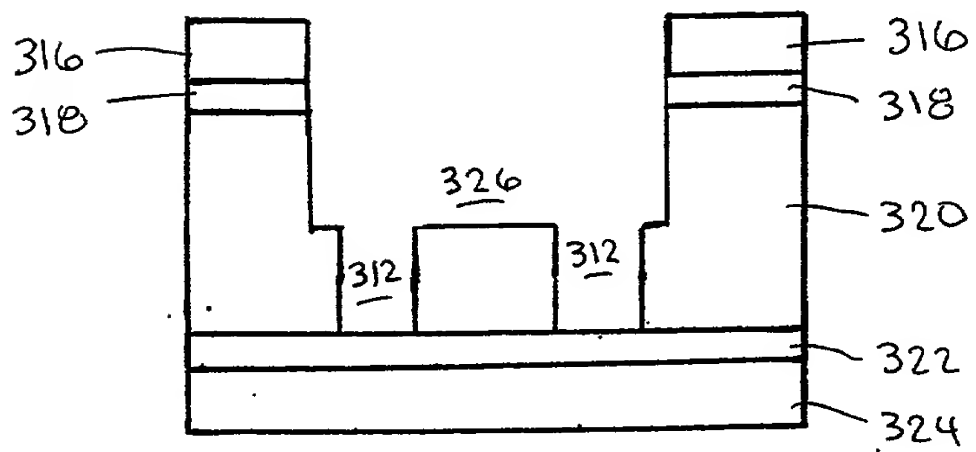


FIG. 6E

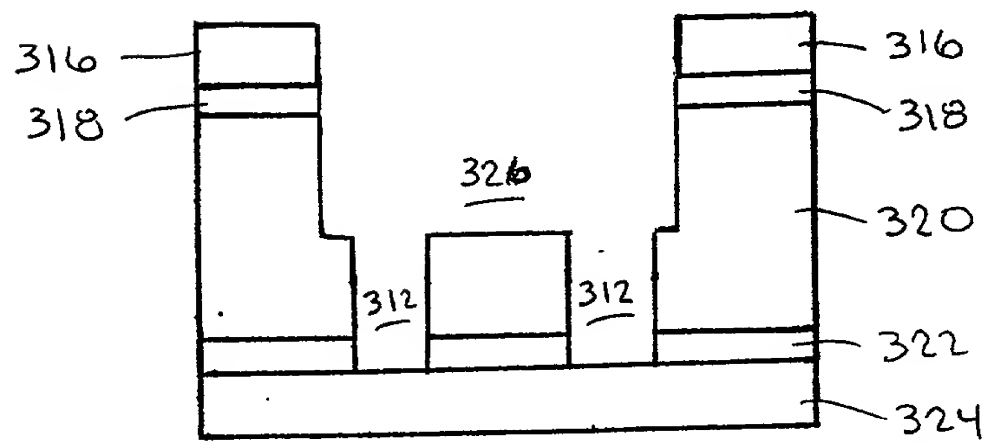


FIG. 6F